ISO9001:2000 Certified SCI Quality System

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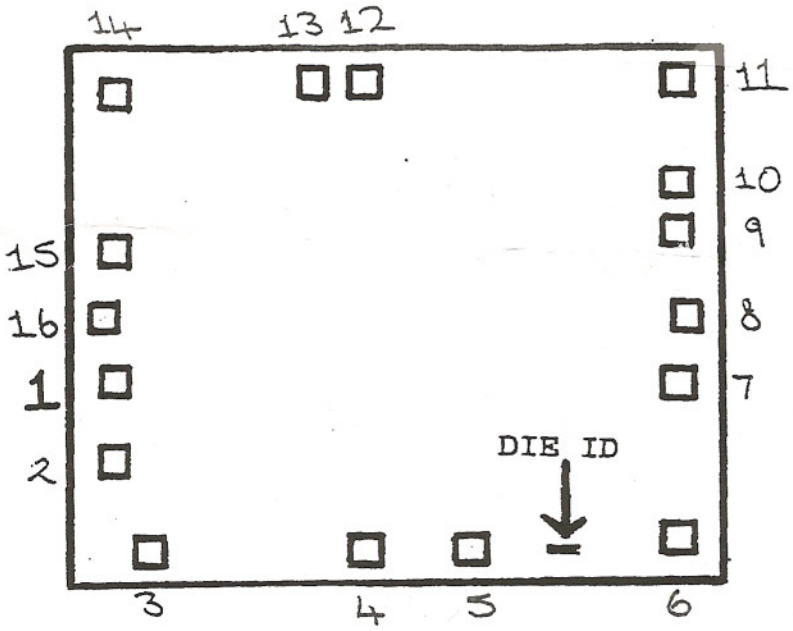
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	T_{1A}	9	$\overline{Q}_B$OUT
2	T_{2A}	10	Q_BOUT
3	C_{DA}	11	B_BINPUT
4	A_AINPUT	12	A_BINPUT
5	B_AINPUT	13	C_{DB}
6	Q_AOUT	14	T_{2B}
7	$\overline{Q}_A$OUT	15	T_{1B}
8	V_{SS}	16	V_{DD}

Top Material:
Backside Material:
Bond Pad Size:
Backside Potential:
Mask Ref:

APPROVED BY:MG	**DIE SIZE :89 x 77**	**DATE: 10/28/08**
MFG:NSC	**THICKNESS:15**	**P/N:CD4538 BH**